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Sp	eciti	ication		
Part Number:	MCC	DT256064C ²	1Y-GM	
Version:	1			
Date:	10/0	4/2015		
	Revi	sion		
Key Attributes Graphic OLED 256 x 64 Green on Black 3V to 5V Parallel and SPI Interface 146.0 x 45.0 mm -40 ~ +70 deg C TAB	huf	MCIB-3-MONO		ply
	Part Number: Version: Date: Date: Key Attributes Graphic OLED 256 x 64 Green on Black 3V to 5V Parallel and SPI Interface 146.0 x 45.0 mm -40 ~ +70 deg C	Part Number: MCC Version: 1 Date: 10/0 Revi Key Attributes Graphic OLED 256 x 64 Green on Black 3V to 5V Parallel and SPI Interface 146.0 x 45.0 mm -40 ~ +70 deg C	Version:1Date:10/04/2015RevisionKey AttributesKey AttributesDisplay ActGraphic OLEDMCIB-3-MONO256 x 64MCIB-3-MONOGreen on BlackMCIB-3-MONO3V to 5VParallel and SPI Interface146.0 x 45.0 mm-40 ~ +70 deg C	Part Number:MCOT256064C1Y-GMVersion:1Date:10/04/2015RevisionKey AttributesGraphic OLED 256 x 64MCIB-3-MONOGreen on Black 3V to 5V Parallel and SPI Interface 146.0 x 45.0 mm -40 ~ +70 deg CMCIB-3-MONO



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1.General Specification

The Features is described as follow:

- Module dimension: 146.0 × 45.0 × 2.05 mm
- Active area: 135.65 × 33.89 mm
- Dot Matrix: 256 x 64 Dots
- Pixel Size: 0.5 × 0.5 mm
- Pixel Pitch: 0.53 × 0.53 mm
- Display Mode : Passive Matrix
- Duty: 1/64 Duty
- Display Color: Green
- IC:SSD1322



Midas Displays OLED Part Number System

MC 1	_	B 216 2 3		* 5	V 6	-	Е 7	W 8	I 9	* 10
1	=	MCO:	Midas Dis	splays OLEI	D					
2	=	Blank:	B : COB (Chip on Boa	ard) T : TAE	3 (Taped Aut	omated Bo	onding)		
3	=	No of dots:	(e.g. 2400	064 = 240 x	64 dots)	(e.g. 2160	5 = 2 x 16	5mm C.H.))	
4	=	Series	A to Z							
5	=	Series Variant:	A to Z and	d 1 to 9 – se	ee addendur	n				
6	=	Operating Temp	Range: A: -30+8 X: -40 +8		-40+80° C	Y: -40 +70)°C Z :	-30+70° C		
7	=	Character Set:		ot Applicable European Fo	e ont Set (Engli	sh/Japanese	e – Wester	n European	ı (K) – Cyri	illic (R))
8	=	Colour:	Y: Yellow	W: White	e B: Blue	R: Red	G: Green	RGB: Fu	ll Colour	
9	=	Interface:	P: Paralle	el I: l'	²C	S: SPI	М	: Multi		
10	=	Voltage Variant	e.g. 3 = 3	V						

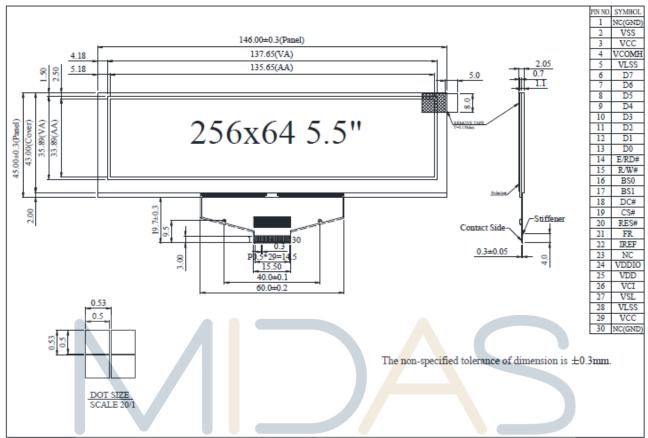
F/Displays/Midas Brand/Midas NEW OLED Part Number System 18 June 2013 2011.doc

Interface Pin Function

Pin Number	Symbol	I/O	Function
Power Su	pply		
26	VCI	Р	Power Supply for Operation This is a voltage supply pin. It must be connected to external source & always be equal to or higher than VDD & VDDIO.
25	VDD	Ρ	Power Supply for Core Logic Circuit This is a voltage supply pin. It can be supplied externally (within the range of 2.4~2.6V) or regulated internally from VCI. A capacitor should be connected between this pin & VSS under all circumstances.
24	VDDIO	Ρ	Power Supply for I/O Pin This pin is a power supply pin of I/O buffer. It should be connected to VDD or external source. All I/O signal should have VIH reference to VDDIO. When I/O signal pins (BS0~BS1, D0~D7, control signals) pull high, they should be connected to VDDIO.
2	VSS	Р	Ground of Logic Circuit This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.
3,29	VCC	Ρ	Power Supply for OLED Panel These are the most positive voltage supply pin of the chip. They must be connected to external source.
5,28	VLSS	Р	Ground of Analog Circuit These are the analog ground pins. They should be connected to VSS externally.
Driver			
22	IREF		<i>Current Reference for Brightness Adjustment</i> This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current lower than 10uA.
4	VCOMH	Р	Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A tantalum capacitor should be connected between this pin and VSS.
27	VSL	Ρ	Voltage Output Low Level for SEG Signal This is segment voltage reference pin. When external VSL is not used, this pin should be left open. When external VSL is used, this pin should connect with resistor and diode to ground.

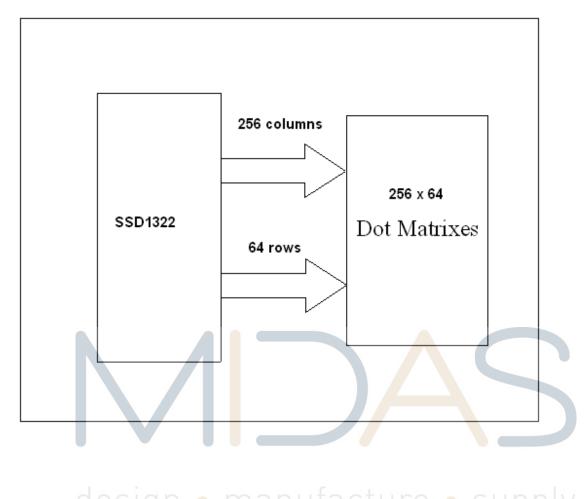
Testing Pa	ds					
21	FR	0	<i>Frame Frequency Triggering Sigr</i> This pin will send out a signal that c driver status. Nothing should be cor be left open individually.	ould be us		
16	BS0	1	Communicating Protocol Select			
17	BS1	tion input.	See the fo	ollowing 1		
			3-wire SPI	1	0	1
			4-wire SPI	0	0	
			8-bit 68XX Parallel	1	1	
			8-bit 80XX Parallel	0	1	
20	RES#		Power Reset for Controller and D		1	
20	RES#		This pin is reset signal input. When of the chip is executed.		low, initiali	zation
19	CS#	I	Chip Select This pin is the chip select input. The communication only when CS# is p		nabled for	MCU
18	D/C#		Data/Command Control This pin is Data/Command control p high, the input at D7~D0 is treated a When the pin is pulled low, the input transferred to the command registe MCU interface signals, please refer Timing Characteristics Diagrams.	as display t at D7~D r. F <mark>o</mark> r deta	data. 0 will be	
14	E/RD#		Read/Write Enable or Read This pin is MCU interface input. Wh 68XX-series microprocessor, this pin Enable (E) signal. Read/write operation pin is pulled high and the CS# is put When connecting to an 80XX-micro the Read (RD#) signal. Data read of this pin is pulled low and CS# is put When serial mode is selected, this put VSS.	n will be u ation is init lled low. processon peration is led low.	used as the iated wher r, this pin ro s initiated v	n this eceives when
15	R/W#	I	Read/Write Select or Write This pin is MCU interface input. Wh 68XX-series microprocessor, this pin Read/Write (R/W#) selection input. read mode and pull it to "Low" for w When 80XX interface mode is select Write (WR#) input. Data write operation pin is pulled low and the CS# is pull When serial mode is selected, this VSS.	n will be u Pull this p rite mode cted, this p ation is init led low.	used as in to "High bin will be t iated wher	he h this
6~13	D7~D0	I/O	Host Data Input/Output Bus These pins are 8-bit bi-directional d	ata bus to	be conne	cted to

			the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. Unused pins must be connected to VSS except for D2 in serial mode.
Reserve			
23	N.C.	-	Reserved Pin The N.C. pin between function pins are reserved for compatible and flexible design.
1,30	N.C. (GND)	-	Reserved Pin (Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground.



4. Counter Drawing & Block Diagram

FUNCTION BLOCK DIAGRAM



*For more information, please refer to Application Note provided by T aae.

5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Operation	VCI	-0.3	4	V	1, 2
Supply Voltage for Logic	VDD	-0.5	2.75	V	1, 2
Supply Voltage for I/O Pins	VDDIO	-0.5	VCI	V	1, 2
Supply Voltage for Display	VCC	-0.5	20	V	1, 2
Operating Temperature	TOP	-40	80	°C	-
Storage Temperature	TSTG	-40	80	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Operation	VCI	Note	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	14	14.5	16	V
High Level Input	VIH	_	0.8×V _{DDIO}	_	V _{DDIO}	V
Low Level Input	VIL		0	_	0.2×V _{DDIO}	V
High Level Output	VOH	_	0.9×V _{DDIO}	_	V _{DDIO}	V
Low Level Output	VOL		0	_	0.1×V _{DDIO}	V
50% Check Board operating	Current	VCC =14.5V	34	36	45	mA

Note: Supply Voltage for Logic = VDD core power supply can be regulated from VCI.

7.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	—	160	—	—	deg
view Angle	(H)φ	—	160	—	_	deg
Contrast Ratio	CR	Dark	2000:1	—	_	_
Response Time	Trise -	—	10	-	μs	
Response nine	T fall	_	—	10	_	μs
Display with 50% check E	Board Brightness		60	80	_	cd/m2
CIEx(Green)		(CIE1931)	0.24	0.28	0.32	_
CIEy(Green)		(CIE1931)	0.59	0.63	0.67	_



8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25℃ / Initial 50% check Board Typical Brightness Value	80,000 Hrs	100,000 Hrs	Note

Note:

1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.

2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.

3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Environmenta Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80 240hrs	
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20 240hrs	
High Temperature/ Humidity Storage	Endurance test app <mark>ly</mark> ing the high temperature and high humidity storage for a long time.	60 ,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40 25 80 30min 5min 30min 1 cycle	-20 /70 100 cycles	
Mechanical Te	st i an a manufa		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	<u>uppty</u>
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

***Supply voltage for OLED system =Operating voltage at 25°C

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

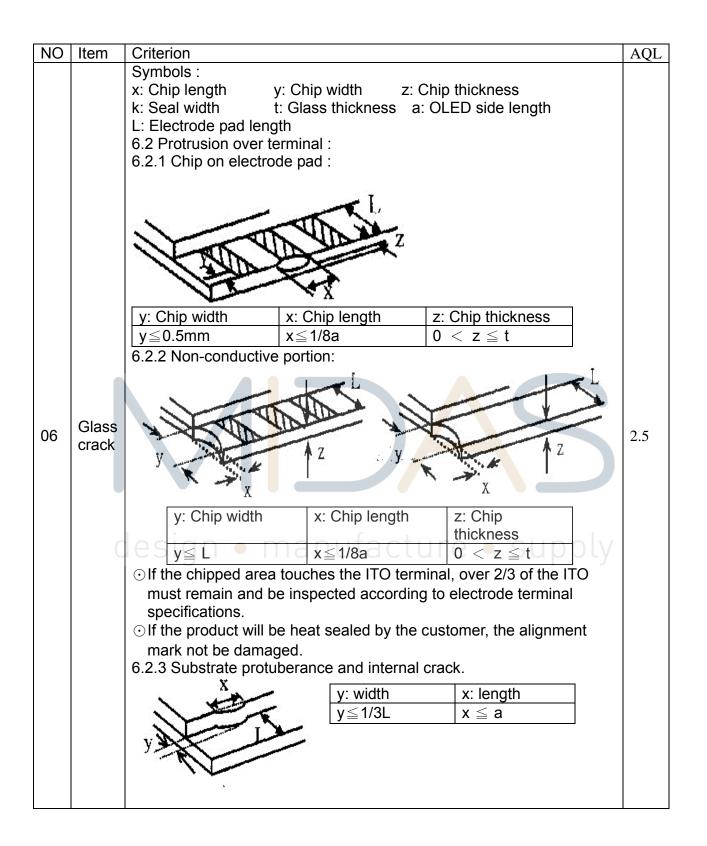
Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 				
02	Black or white spots on OLED (display only)	three white or bl 2.2 Densely spa 3mm.	ack spots ced: No m	on display ≦0.25n present. ore than two spots		2.5
03	OLED black spots, white spots, contamina tion (non-displ ay)	3.1 Round type following drawin $\Phi = (x + y) / 2$		SIZE $\Phi \le 0.10$ $0.10 <$ $\Phi \le 0.20$ $0.20 <$ $\Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1	2.5
		3.2 Line type : (/	As followin	g drawing)		
			Length L≦3.0 L≦2.5		Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vi judge using blac specifications, n to find, must che specify direction	k spot ot easy eck in	Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO	Item	Criterion	AQL		
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:			
06	Chipped glass	z: Chip thicknessy: Chip widthx: Chip length $Z \le 1/2t$ Not over viewing $x \le 1/8a$ $1/2t < z \le 2t$ Not exceed $1/3k$ $x \le 1/8a$ \odot If there are 2 or more chips, x is total length of each chip.6.1.2 Corner crack:	2.5		
	des	The chine this lease the chine width	1		
		z: Chip thickness y: Chip width x: Chip length	41		
		Z \leq 1/2tNot over viewing areax \leq 1/8a			
		$1/2t < z \le 2t$ Not exceed 1/3k $x \le 1/8a$			
		\odot If there are 2 or more chips, x is the total length of each chip.			



NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	 2.5 2.5 2.5 2.5 0.65 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on	2.5
		product.	2.5
	Quant	12.4 The IC on the TCP may not be damaged, circuits.	2.5
12		12.5 The uppermost edge of the protective strip on the	
		interface pin must be present or look as if it cause the	2.5
	General	interface pin to sever.	25
	appearance	12.6 The residual rosin or tin oil of soldering (component or	2.5 0.65
		chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	0.00
		12.10 Product packaging must the same as specified on	0.65
		packaging specification sheet.	
		12.11 Product dimension and structure must conform to	
		product specification sheet.	

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major Manuf	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pizel C Hill Light Fizel

11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) T aaæ has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)

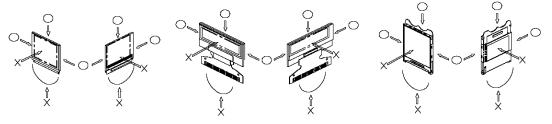
(11) T a are have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, T are have the right to modify the version.)

11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.(We recommend you to store these modules in the packaged state when they were shipped from T aa. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)

(4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.

- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.

